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PC1

U.S. Application No.
Unknown

International Application No.
PCT/JP00/04215

Attorney Docket No.
TOYAM83.001APC

Date: December 27, 2001

10/019753
JC10 Rec'd PCT/PTO 27 DEC 2001

**TRANSMITTAL LETTER TO THE UNITED STATES DESIGNATED/ELECTED OFFICE (DO/EO/US)
CONCERNING A FILING UNDER 35 USC 371**

International Application No.: PCT/JP00/04215
International Filing Date: June 27, 2000
Priority Date Claimed: June 28, 1999
Title of Invention: LOW-HYGROSCOPICITY LOW-BIREFRINGENCE RESIN
COMPOSITIONS, MOLDING MATERIAL OBTAINED THEREFROM,
SHEET OR FILM, AND OPTICAL PART
Applicant(s) for DO/EO/US: Yukihiro YAMASHITA; Shuichi IWATA; Tetsuo YAMANAKA;
Akihiro YOSHIDA; Keiko USHIKUBO

Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. (X) This is a **FIRST** submission of items concerning a filing under 35 USC 371.
2. () This is a **SECOND** or **SUBSEQUENT** submission of items concerning a filing under 35 USC 371.
3. (X) This express request to begin national examination procedures (35 USC 371(f)) at any time rather than delay examination until the expiration of the applicable time limit set in 35 USC 371(b) and PCT Articles 22 and 39(1).
4. (X) A proper Demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date.
5. (X) A copy of the International Application as filed (35 USC 371(c)(2))
 - a) () is transmitted herewith (required only if not transmitted by the International Bureau).
 - b) (X) has been transmitted by the International Bureau.
 - c) (X) a copy of Form PCT/1B/308 is enclosed.
 - d) () is not required, as the application was filed in the United States Receiving Office (RO/US).
6. (X) A translation of the International Application into English (35 USC 371(c)(2)).
7. (X) Amendments to the claims of the International Application under PCT Article 19 (35 USC 371(c)(3)).
 - a) () are transmitted herewith (required only if not transmitted by the International Bureau).
 - b) () have been transmitted by the International Bureau.
 - c) () have not been made; however, the time limit for making such amendments has NOT expired.
 - d) (X) have not been made and will not be made.
8. () A translation of the amendments to the claims under PCT Article 19 (35 USC 371(c)(3)).
9. () An oath or declaration of the inventor(s) (35 USC 371(c)(4)).
10. () A copy of the International Preliminary Examination Report with any annexes thereto, such as any amendments made under PCT Article 34.

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11. (X) A translation of the annexes, such as any amendments made under PCT Article 34, to the International Preliminary Examination Report under PCT Article 36 (35 USC 371(c)(5)).
 12. () An Information Disclosure Statement under 37 CFR 1.97 and 1.98.
 13. () An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included.
 14. (X) A FIRST preliminary amendment.
() A SECOND or SUBSEQUENT preliminary amendment.
 15. () A substitute specification.
 16. () A power of attorney and/or address letter.
 17. () International Application as published.
 18. (X) The following related documents are enclosed:
First page of published International application;
Copy of Form IPEA/210;
Copy of PCT/RO/101;
Copy of Form PCT/IB/304;
Copy of Form PCT/IB/332.
 19. (X) A return prepaid postcard.
 20. (X) The following fees are submitted:

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				FEES
BASIC FEE				\$890
CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE	
Total Claims	30 - 20 =	10 ×	\$18	\$180
Independent Claims	3 - 3 =	0 ×	\$84	\$ 0
Multiple dependent claims(s) (if applicable)			\$280	\$ 0
TOTAL OF ABOVE CALCULATIONS				\$1,070
Reduction by 1/2 for filing by small entity (if applicable). Verified Small Entity statement must also be filed. (NOTE 37 CFR 1.9, 1.27, 1.28)				\$
TOTAL NATIONAL FEE				\$1,070
TOTAL FEES ENCLOSED				\$1,070
amount to be refunded:				\$
amount to be charged:				\$

21. (X) The fee for later submission of the signed oath or declaration set forth in 37 CFR 1.492(e) will be paid upon submission of the declaration.
22. (X) A check in the amount of \$1,070 to cover the above fees is enclosed.
23. () Fee for recording the enclosed assignment (37 CFR 1.21(h)). The assignment must be accompanied by an appropriate cover sheet (37 CFR 3.28, 3.31). \$40 per property.
24. (X) The Commissioner is hereby authorized to charge only those additional fees which may be required, now or in the future, to avoid abandonment of the application, or credit any overpayment to Deposit Account No. 11-1410.

NOTE: Where an appropriate time limit under 37 CFR 1.494 or 1.495 has not been met, a petition to revive (37 CFR 1.137(a) or (b)) must be filed and granted to restore the application to pending status.

SEND ALL CORRESPONDENCE TO:

Che S. Chereskin

Che Swyden Chereskin, Ph.D.

Reg. No. 41,466

Customer No. 20,995

TOYAM83.001APC

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Yamashita, et al.)	Group Art Unit: unknown
)	
Appl. No.	:	unknown)	
)	
Filed	:	herewith)	
)	
For	:	LOW-HYGROSCOPICITY)	
		LOW-BIREFRINGENCE)	
		RESIN COMPOSITIONS,)	
		MOLDING MATERIAL,)	
		SHEET OR FILM OBTAINED)	
		THEREFROM, AND OPTICAL)	
		PART)	
Examiner	:	unknown		

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Preliminary to examination on the merits, please amend the above-captioned U.S. application as follows:

IN THE SPECIFICATION

On page 1 of the Specification, after the Title of the Invention and before the Technical Field statement starting on line 8, please insert ---This is the U.S. National Phase under 35 U.S.C. § 371 of International Application PCT/JP00/04215, filed June 27, 2000, which was published in a language other than English, which claims priority of Japanese Patent Application No. 11-181181, filed June 28, 1999; Japanese Patent Application No. 11-181182, filed June 28, 1999; Japanese Patent Application No. 2000-24774, filed January 28, 2000; Japanese Patent Application No. 2000-24775, filed January 28, 2000; and Japanese Patent Application No. 2000-24776, filed January 28, 2000.---

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Filed : herewith

On page 75 before Claim 1, please delete the word "CLAIMS" and substitute therefore --
-WHAT IS CLAIMED IS---.

Please amend the paragraph beginning at page 7, line 13 as follows:

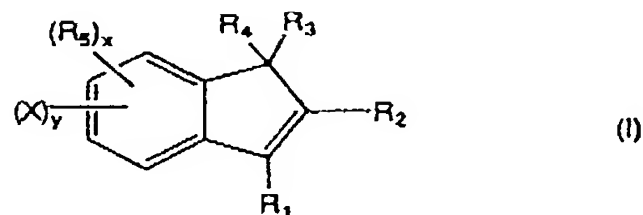
The present invention relates to the following items (1) to (22).

(1) A resin composition (a) comprising the following polymers (A), and (B) and/or (C):

(A) a polymer comprising one or more kinds of indene and indene derivatives
represented by the following general formula (I);

(B) a polymer comprising polystyrene or a polystyrene derivative; and

(C) a polymer comprising a monomer copolymerizable with styrene or a styrene
derivative:



(wherein R_1 , R_2 , R_3 , R_4 , and R_5 may be the same or different, and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group. X represents a hydrogen atom, a halogen atom, an acyl group, an alkoxy group or a nitrile group. x represents 0 or an integer of 1 to 4, and y represents an integer of 1 to 4, where $x + y = 4$.)

(2) The resin composition (a) according to (1), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (A), and (B) and/or (C).

(3) The resin composition (a) according to (1) or (2), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

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(4) The resin composition (a) according to any one of (1) to (3), wherein the weight-average molecular weight of the polymer (A) is lower than 80000.

(5) The resin composition (a) according to any one of (1) to (4), wherein the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is 50000 or higher.

(6) The resin composition (a) according to any one of (1) to (5), wherein the content of the polymer (A) is 30 to 90% by weight of the total of the resin composition (a).

(7) A resin composition (b) comprising the following polymers (F), (G) and (H):

(F) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I);

(G) a polymer comprising polystyrene or a polystyrene derivative; and

(H) a graft polymer having a structure where a polymer comprising at least one kind of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative.

(8) The resin composition (b) according to (7), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (F), (G) and (H).

(9) The resin composition (b) according to (7) or (8), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(10) The resin composition (b) according to any one of (7) to (9), wherein the weight-average molecular weight of the polymer (F) is 4000 or higher.

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Filed : **herewith**

(11) The resin composition (b) according to any one of (7) to (10), wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

(12) The resin composition (b) according to any one of (7) to (11), wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

(13) A resin composition (c) comprising the following polymers (I) and (J), diphenylsilicone (D), and a phenolic antioxidant (E):

(I) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof; and

(J) a polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

(14) The resin composition (c) according to (13), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(15) The resin composition (c) according to (13) or (14), wherein the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) is 0.01 to 5 mol% of the total of the resin composition (c).

(16) The resin composition (c) according to any one of (13) to (15), wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

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Filed : **herewith**

(17) The resin composition (c) according to any one of (13) to (16), wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

(18) The resin composition (c) according to any one of (13) to (17), wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

(19) A molding material obtained by molding a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(20) A sheet obtained from a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(21) A film obtained from a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(22) An optical part using the molding material, the sheet or the film according to any one of (19) to (21).

Please amend the paragraph beginning at page 12, line 26 as follows:

The indene derivatives for use in the above polymer (A) include those represented by the above general formula (I), wherein R_1 , R_2 , R_3 , R_4 , and R_5 may be the same or different, and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group.

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 Filed : herewith

Please amend the paragraph beginning at page 16, line 22 as follows:

α -substituted alkylstyrenes that may be employed include, for example, α -methylstyrene, α -ethylstyrene, α -propylstyrene, α -n-butylstyrene, α -isobutylstyrene, α -t-butylstyrene, α -n-pentylstyrene, α -2-methylbutylstyrene, α -3-methylbutylstyrene, α -t-pentylstyrene, α -n-hexylstyrene, α -2-methylpentylstyrene, α -3-methylpentylstyrene, α -1-methylpentylstyrene, α -2,2-dimethylbutylstyrene, α -2,3-dimethylbutylstyrene, α -2,4-dimethylbutylstyrene, α -3,3-dimethylbutylstyrene, α -3,4-dimethylbutylstyrene, α -4,4-dimethylbutylstyrene, α -2-ethylbutylstyrene, α -1-ethylbutylstyrene, α -cyclohexylstyrene, and the like. Those listed hereinbefore are simply examples and α -substituted alkylstyrenes are not limited thereto. These may be used singly or in combination with two or more.

Please amend the paragraph beginning at page 22, line 10 as follows:

Catalysts for use in radical polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts include, for example, peroxides such as benzoyl peroxide, lauroyl peroxide, methyl ethyl ketone peroxide and the like. Those listed hereinbefore are simply examples, and the catalysts are not limited thereto. These may be used singly or in combination with two or more.

Please amend the paragraph beginning at page 24, line 3 as follows:

In the resin composition (a), the weight-average molecular weight of the polymer (A) is preferably lower than 80000, more preferably lower than 40000. If the weight-average molecular weight of the polymer (A) is higher than 80000, fluidity and transparency of the resin composition (a) tend to decrease.

Please amend the paragraph beginning at page 30, line 6 as follows:

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Filed : **herewith**

The graft polymer (H) for use in the resin composition (b) has a structure where a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative. That is, the graft polymer (H) has a backbone unit of the polymer comprising a monomer copolymerizable with styrene or a styrene derivative and branch units of the polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I).

Please amend the paragraph beginning at page 37, line 4 as follows:

In the resin composition (c) of the present invention, the above polymer (J) comprises styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, and it has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

Please amend the paragraph beginning at page 37, line 8 as follows:

Styrene derivatives for use in the polymer (J) include, for example, nucleus-substituted alkylstyrenes, nucleus-substituted aromatic styrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxy styrenes, alkyl vinyl ethers, aromatic vinyl ethers, and the like, and specifically include the same monomers as the styrene monomers for use in the polymer (B) of the resin composition (a).

Please amend the paragraph beginning at page 51, line 16 as follows:

Placed in a 100-ml flask were 14.0 g of styrene, 5.0 g of 4-methylstyrene, 1.0 g of butyl acrylate and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70 °C for 12 hours with stirring. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50 °C for about 2 hours

Appl. No. : unknown
Filed : herewith

to obtain a polymer (C). The weight-average molecular weight of the polymer obtained was 240000.

IN THE CLAIMS

Please amend claims 3-6, 9-12, and 15-22 as follows:

Claim 3. (Amended) The resin composition (a) according to claim 1, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

Claim 4. (Amended) The resin composition (a) according to claim 1, wherein the weight-average molecular weight of the polymer (A) is lower than 80000.

Claim 5. (Amended) The resin composition (a) according to claim 1, wherein the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is 50000 or higher.

Claim 6. (Amended) The resin composition (a) according to claim 1, wherein the content of the polymer (A) is 30 to 90% by weight of the total of the resin composition (a).

Claim 9. (Amended) The resin composition (b) according to claim 7, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

Claim 10. (Amended) The resin composition (b) according to claim 7, wherein the weight-average molecular weight of the polymer (F) is 4000 or higher.

Claim 11. (Amended) The resin composition (b) according to claim 7, wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

Claim 12. (Amended) The resin composition (b) according to claim 7, wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

Appl. No. : **unknown**
Filed : **herewith**

Claim 15. (Amended) The resin composition (c) according to claim 13, wherein the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) are/is 0.01 to 5 mol% of the total of the resin composition (c).

Claim 16. (Amended) The resin composition (c) according to claim 13, wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

Claim 17. (Amended) The resin composition (c) according to claim 13, wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

Claim 18. (Amended) The resin composition (c) according to claim 13, wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

Claim 19. (Twice Amended) A molding material for use in optical parts, the molding material being obtained by molding a resin composition according to claim 1.

Claim 20. (Twice Amended) A sheet for use in optical parts, the sheet being obtained from a resin composition according to claim 1.

Claim 21. (Twice Amended) A film for use in optical parts, the film being obtained from a resin composition according to claim 1.

Claim 22. (Amended) An optical part using the molding material, the sheet or the film according to claim 19.

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Filed : herewith

Please add the following claims 23-30:

Claim 23. (New) A molding material for use in optical parts, the molding material being obtained by molding a resin composition according to claim 7.

Claim 24. (New) A molding material for use in optical parts, the molding material being obtained by molding a resin composition according to claim 13.

Claim 25. (New) A sheet for use in optical parts, the sheet being obtained from a resin composition according to claim 7.

Claim 26. (New) A sheet for use in optical parts, the sheet being obtained from a resin composition according to claim 13.

Claim 27. (New) A film for use in optical parts, the film being obtained from a resin composition according to claim 7.

Claim 28. (New) A film for use in optical parts, the film being obtained from a resin composition according to claim 13.

Claim 29. (New) An optical part using the molding material, the sheet or the film according to claim 20.

Claim 30. (New) An optical part using the molding material, the sheet or the film according to claim 21.

REMARKS

The specification has been amended for clarity and the claims have been amended to conform with the rules of practice before the U.S. Patent and Trademark Office. The specification has been amended to recite the International Application and priority applications. The word "CLAIMS" has been deleted and substituted by "WHAT IS CLAIMED IS" so that subsequently appearing claims will be the object of a sentence as specified by M.P.E.P. section

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Filed : herewith

608.01(m). As a result of this preliminary amendment, Claims 23-30 have been added and Claims 3-6, 9-12, and 15-22 have been amended. Accordingly, Claims 1-30 are presented for examination. No new matter is being added herewith.

The specific changes to the specification and the amended claims are shown on a separate set of pages attaches hereto and entitled VERSION WITH MARKINGS TO SHOW CHANGES MADE, which follows the signature page of this Amendment. On this set of pages, insertions are underlined and deletions are struck through.

Conclusion

Should there be any questions concerning this application, the Examiner is invited to contact the undersigned agent at the telephone number appearing below. Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: Dec. 27, 2001

By: Che S. Chereskin
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Filed : herewith

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the specification:

The paragraph beginning at page 7, line 13 has been amended as follows:

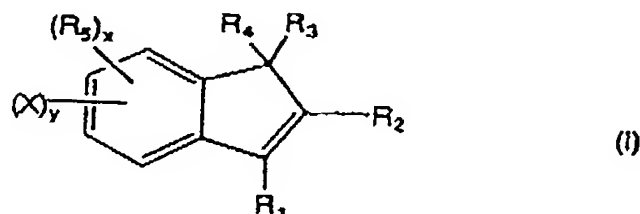
The present invention relates to the following items (1) to (22).

(1) A resin composition (a) comprising the following polymers (A), and (B) and/or (C):

(A) a polymer comprising one or more kinds of indene and indene derivatives represented by the following general formula (I);

(B) a polymer comprising polystyrene or a polystyrene derivative; and

(C) a polymer comprising a monomer copolymerizable with styrene or a styrene derivative:



(wherein R_1 , R_2 , R_3 , R_4 , and R_5 ~~and~~ R_6 may be the same or different, and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group. X represents a hydrogen atom, a halogen atom, an acyl group, an alkoxy group or a nitrile group. x represents 0 or an integer of 1 to 4, and y represents an integer of 1 to 4, where $x + y = 4$).

(2) The resin composition (a) according to (1), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (A), and (B) and/or (C).

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(3) The resin composition (a) according to (1) or (2), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(4) The resin composition (a) according to any one of (1) to (3), wherein the weight-average molecular weight of the polymer (A) is lower than 80000.

(5) The resin composition (a) according to any one of (1) to (4), wherein the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is 50000 or higher.

(6) The resin composition (a) according to any one of (1) to (5), wherein the content of the polymer (A) is 30 to 90% by weight of the total of the resin composition (a).

(7) A resin composition (b) comprising the following polymers (F), (G) and (H):

(F) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I);

(G) a polymer comprising polystyrene or a polystyrene derivative; and

(H) a graft polymer having a structure where a polymer comprising at least one kind of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative.

(8) The resin composition (b) according to (7), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (F), (G) and (H).

(9) The resin composition (b) according to (7) or (8), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

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Filed : **herewith**

(10) The resin composition (b) according to any one of (7) to (9), wherein the weight-average molecular weight of the polymer (F) is 4000 or higher.

(11) The resin composition (b) according to any one of (7) to (10), wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

(12) The resin composition (b) according to any one of (7) to (11), wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

(13) A resin composition (c) comprising the following polymers (I) and (J), diphenylsilicone (D), and a phenolic antioxidant (E):

(I) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof; and

(J) a polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

(14) The resin composition (c) according to (13), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(15) The resin composition (c) according to (13) or (14), wherein the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) is 0.01 to 5 mol% of the total of the resin composition (c).

Appl. No. : **unknown**
Filed : **herewith**

(16) The resin composition (c) according to any one of (13) to (15), wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

(17) The resin composition (c) according to any one of (13) to (16), wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

(18) The resin composition (c) according to any one of (13) to (17), wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

(19) A molding material obtained by molding a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(20) A sheet obtained from a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(21) A film obtained from a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(22) An optical part using the molding material, the sheet or the film according to any one of (19) to (21).

The paragraph beginning at page 12, line 26 has been amended as follows:

The indene derivatives for use in the above polymer (A) include those represented by the above general formula (I), wherein R_1 , R_2 , R_3 , R_4 , and R_5 , ~~and~~ R_6 may be the same or different,

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and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group.

The paragraph beginning at page 16, line 22 has been amended as follows:

α -substituted alkylstyrenes that may be employed include, for example, α -methylstyrene, α -ethylstyrene, α -propylstyrene, α -n-butylstyrene, α -isobutylstyrene, α -t-butylstyrene, α -n-pentylstyrene, α -2-methylbutylstyrene, α -3-methylbutylstyrene, ~~α -t-butylstyrene~~, α -t-pentylstyrene, α -n-hexylstyrene, α -2-methylpentylstyrene, α -3-methylpentylstyrene, α -1-methylpentylstyrene, α -2,2-dimethylbutylstyrene, α -2,3-dimethylbutylstyrene, α -2,4-dimethylbutylstyrene, α -3,3-dimethylbutylstyrene, α -3,4-dimethylbutylstyrene, α -4,4-dimethylbutylstyrene, α -2-ethylbutylstyrene, α -1-ethylbutylstyrene, α -cyclohexylstyrene, and the like. Those listed hereinbefore are simply examples and α -substituted alkylstyrenes are not limited thereto. These may be used singly or in combination with two or more.

The paragraph beginning at page 22, line 10 has been amended as follows:

Catalysts for use in radical polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts include, for example, peroxides such as benzoyl peroxide, ~~lauryl~~ lauroyl peroxide, methyl ethyl ketone peroxide and the like. Those listed hereinbefore are simply examples, and the catalysts are not limited thereto. These may be used singly or in combination with two or more.

The paragraph beginning at page 24, line 3 has been amended as follows:

In the resin composition (a), the weight-average molecular weight of the polymer (A) is preferably lower than 80000, more preferably lower than 40000. If the weight-average molecular

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weight of the polymer (A) is ~~lower~~ higher than 80000, fluidity and transparency of the resin composition (a) tend to decrease.

The paragraph beginning at page 30, line 6 has been amended as follows:

The graft polymer (H) for use in the resin composition (b) has a structure where a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative. That is, the graft polymer (H) has a backbone unit of the polymer comprising a monomer copolymerizable with styrene or a styrene derivative and branch units of the polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I).

The paragraph beginning at page 37, line 4 has been amended as follows:

In the resin composition (c) of the present invention, the above polymer (J) comprises styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, and it has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

The paragraph beginning at page 37, line 8 has been amended as follows:

~~Monomers copolymerizable with styrene or a styrene derivative~~ Styrene derivatives for use in the polymer (J) include, for example, nucleus-substituted alkylstyrenes, nucleus-substituted aromatic styrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxy styrenes, alkyl vinyl ethers, aromatic vinyl ethers, and the like, and specifically include the same monomers as the styrene monomers for use in the polymer (B) of the resin composition (a).

The paragraph beginning at page 51, line 16 has been amended as follows:

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Placed in a 100-ml flask were 14.0 g of styrene, 5.0 g of 4-methylstyrene, 1.0 g of butyl acrylate and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70 °C for 12 hours with stirring. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50 °C for about 2 hours to obtain a polymer (BC). The weight-average molecular weight of the polymer obtained was 240000.

In the claims:

Claims 3-6, 9-12, and 15-22 have been amended as follows:

Claim 3. (Amended) The resin composition (a) according to claim 1-~~or 2~~, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

Claim 4. (Amended) The resin composition (a) according to ~~any one of claims 1 to 3~~ claim 1, wherein the weight-average molecular weight of the polymer (A) is lower than 80000.

Claim 5. (Amended) The resin composition (a) according to ~~any one of claims 1 to 4~~ claim 1, wherein the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is 50000 or higher.

Claim 6. (Amended) The resin composition (a) according to ~~any one of claims 1 to 5~~ claim 1, wherein the content of the polymer (A) is 30 to 90% by weight of the total of the resin composition (a).

Claim 9. (Amended) The resin composition (b) according to claim 7-~~or 8~~, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

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Claim 10. (Amended) The resin composition (b) according to ~~any one of claims 7 to 9~~claim 7, wherein the weight-average molecular weight of the polymer (F) is 4000 or higher.

Claim 11. (Amended) The resin composition (b) according to ~~any one of claims 7 to 10~~claim 7, wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

Claim 12. (Amended) The resin composition (b) according to ~~any one of claims 7 to 11~~claim 7, wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

Claim 15. (Amended) The resin composition (c) according to claim 13 ~~or 14~~, wherein the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) are/is 0.01 to 5 mol% of the total of the resin composition (c).

Claim 16. (Amended) The resin composition (c) according to ~~any one of claims 13 to 15~~claim 13, wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

Claim 17. (Amended) The resin composition (c) according to ~~any one of claims 13 to 16~~claim 13, wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

Claim 18. (Amended) The resin composition (c) according to ~~any one of claims 13 to 17~~claim 13, wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

Claim 19. (Twice Amended) A molding material for use in optical parts, the molding material being obtained by molding a resin composition ~~selected from the resin composition (a)~~ according

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to claim 1, ~~the resin composition (b) according to claim 7 and the resin composition (c)~~
~~according to claim 13.~~

Claim 20. (Twice Amended) A sheet for use in optical parts, the sheet being obtained from a
resin composition ~~selected from the resin composition (a) according to claim 1, the resin~~
~~composition (b) according to claim 7 and the resin composition (c) according to claim 13.~~

Claim 21. (Twice Amended) A film for use in optical parts, the film being obtained from a resin
composition ~~selected from the resin composition (a) according to claim 1, the resin composition~~
~~(b) according to claim 7 and the resin composition (c) according to claim 13.~~

Claim 22. (Amended) An optical part using the molding material, the sheet or the film according
to ~~any one of claims 19 to 21~~ claim 19.

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DESCRIPTION

LOW-HYGROSCOPICITY LOW-BIREFRINGENCE RESIN COMPOSITIONS,
5 MOLDING MATERIAL, SHEET OR FILM OBTAINED THEREFROM, AND OPTICAL
PART

TECHNICAL FIELD

10 The present invention relates to resin compositions
having low hygroscopicity, low birefringence and low
permittivity, being excellent in fluidity, causing little
change in color in heating, and being excellent in mold release
characteristics in injection molding, and to a molding material,
15 a sheet, or a film obtained by molding these resin compositions
and to an optical part.

BACKGROUND ART

20 Many of the monomers having an unsaturated bond with
reaction activity can yield a polymer by selecting a catalyst
that can cause cleavage of the unsaturated bond to initiate
a chain reaction and appropriate reaction conditions. In
general, there are an extremely wide variety of kinds of the
25 monomers having an unsaturated bond, so that kinds of the resins

that can be obtained therefrom also come in a great many varieties. However, there are relatively few kinds of monomers that can yield a product having a high molecular weight of 10,000 or higher, which is generally called as a high molecular compound. For example, typical monomers include ethylene, substituted ethylenes, propylene, substituted propylenes, styrene, alkylstyrenes, alkoxy styrenes, norbornene, various acrylic esters, butadiene, cyclopentadiene, dicyclopentadiene, isoprene, maleic anhydride, maleimide, fumarate esters, allyl compounds, and the like. Various kinds of resins are synthesized from these monomers or various combinations thereof.

The use of these resins is mainly limited to the field of relatively inexpensive commercial equipment, and there is little application to the field of high technology such as semiconductor-related materials and the like. This is because heat resistance, low hygroscopicity and permittivity have not been simultaneously achieved.

For instance, in the field of semiconductor-related materials, on account of increased density in integration in recent years, it has been desired to further attain low permittivity in addition to heat resistance and low hygroscopicity that have already been achieved. In order to achieve low permittivity, it is indispensable in principle to decrease the number of polar groups in a resin. At present,

polyimides are often employed as resins for semiconductors. However, a lot of hard work has been made to achieve low permittivity because polyimides contain many carbonyl groups in a resin skeleton. As measures to overcome the situation, 5 researches using the monomers containing fluorine have been done extensively, but sufficiently low permittivity has not been achieved. Moreover, there are some problems such as the rising price of resins, complicated synthesis of resins, and the like.

10 As another method, attempts to synthesize a polymer comprising a hydrocarbon containing no polar groups have been made. An example of such a polymer is a series of polymers called cyclic polyolefins. Specific examples include a polymer obtained by hydrogenating polynorbornene, or a polymer 15 comprising polydicyclopentene and a derivative thereof. Although these polymers can exhibit extremely low permittivity, they have problems such as low heat resistance and very high permeability of water in spite of extremely low water absorption. In particular, the high permeability of water is a common 20 characteristic of polyolefins, and it is considered to be extremely difficult to solve this problem.

Another example is a syndiotactic polystyrene synthesized by using Ziegler-Natta catalyst or Kaminsky catalysts. This polymer has a structure that 25 three-dimensional positions of the benzene rings to the

backbone are located alternately in the opposite directions, so that it is possible to attain very high heat resistance and at the same time extremely low water absorption, extremely low permeability of water and very low level of permittivity.

5 However, this polymer has such high crystallinity that it has a problem of considerably poor adhesion to a base material and also has another problem that methods of processing it are markedly limited because it is insoluble in any solvents. That is, at present, a polymer that can overcome the

10 above-mentioned problems has not been developed yet.

On the other hand, typical polymers for optical uses, such as optical lenses, optical waveguide materials and the like include acrylic resins and polyolefin resins. Acrylic resins have characteristics of having excellent transparency

15 and workability and extremely low birefringence. However, they have disadvantages that they have high hygroscopicity, relatively low heat resistance and low toughness. By contrast, polyolefin resins have excellent heat resistance and extremely low hygroscopicity, but they are inferior to acrylic resins

20 in transparency and low birefringence. That is, both of acrylic resins and polyolefin resins have both advantages and disadvantages, and thus it has strongly been desired to develop a resin compensating for the disadvantages of acrylic resins and polyolefin resins.

25 Thus, in order to improve acrylic resins, that is, to

overcome the disadvantages such as high hygroscopicity and low heat resistance, a lot of investigations have been carried out. For example, there is a method of improving hygroscopicity and heat resistance by using a monomer having a bulky substituent (disclosed in Japanese Patent No. 2678029). Although this invention is indeed effective to a certain extent, the improved acrylic resin is still inferior to polyolefin resins in hygroscopicity. This invention poses still another problem that there is a drastic reduction in toughness and strength because a bulky substituent is present in a side chain, so that the resin becomes likely to be broken particularly in molding processing. Although there is a method of attempting to give toughness to the resin by copolymerizing a monomer that gives flexibility for the purpose of improving this, decrease in heat resistance is inevitable, and thus the effect of introducing a bulky substituent is weakened.

Polyolefin resins have extremely great advantages of low hygroscopicity and high heat resistance as resins of optical use, but the high birefringence thereof has become a great disadvantage with the increasing sophistication of optical devices in recent years. Therefore, many attempts to lower the birefringence of polyolefin resins have been made particularly recently.

Such an example is disclosed in Japanese Patent Application Laid-open No. Hei 8-110402. This invention is

that a resin or a low molecular weight compound having birefringence with the opposite sign to the birefringence of a polyolefin resin is mixed to the polyolefin resin to compensate the birefringence intrinsic to the resin, thereby reducing the birefringence of the resin mixture to zero. In this method, it is required that a resin to be mixed and a polyolefin resin be completely compatible. However, compatibility of a polyolefin resin and a resin that is claimed is insufficient in the above invention, so that satisfactory effect cannot be achieved.

Thus, in order to realize as complete compatibility as possible, a method of adding a compatibility agent as the third component is carried out as a polymer alloying technique, and it is specifically described in U.S. Patent No. 4,373,065. In order to mix both of the above highly homogeneously, both should be in a molten state or a solution state. However, it is considered that it is extremely difficult to obtain a practical polymer material that is highly homogeneous and has no birefringence as a whole by using any physical method.

A method to solve these problems is disclosed in Japanese Patent Application No. Hei 8-199901. This method has some problems such as remaining a portion of a resin in a die when removing a product from the die in injection molding of the resin composition or breaking a product in mold releasing. Moreover, it has a disadvantage in that the color of a product

changes while the resin stays in a molding machine for a long time.

DISCLOSURE OF THE INVENTION

5 The present invention provides resin compositions having low hygroscopicity, low birefringence and low permittivity, excelling in fluidity, causing little change in color upon heating, and being excellent in mold release characteristics in injection molding, a molding material, a sheet or a film
10 obtained by molding these resin compositions, and an optical part.

 The present invention relates to the following items (1) to (22).

15

(1) A resin composition (a) comprising the following polymers (A), and (B) and/or (C):

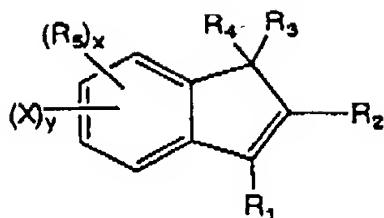
(A) a polymer comprising one or more kinds of indene and indene derivatives represented by the following general formula (I);

20 (B) a polymer comprising polystyrene or a polystyrene derivative; and

(C) a polymer comprising a monomer copolymerizable with styrene or a styrene derivative:

25

8



(I)

5 (wherein R_1 , R_2 , R_3 , R_4 , R_5 and R_6 may be the same or different, and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group. X represents a hydrogen atom,
 10 a halogen atom, an acyl group, an alkoxy group or a nitrile group. x represents 0 or an integer of 1 to 4, and y represents an integer of 1 to 4, where $x + y = 4$.)

(2) The resin composition (a) according to (1), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is
 15 added to the resin composition comprising the polymers (A), and (B) and/or (C).

(3) The resin composition (a) according to (1) or (2), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is
 20 in the range of -2×10^{-6} to 2×10^{-6} .

(4) The resin composition (a) according to any one of (1) to (3), wherein the weight-average molecular weight of the polymer (A) is lower than 80000.

(5) The resin composition (a) according to any one of (1) to
 25 (4), wherein the weight-average molecular weight(s) of the

polymer (B) and/or the polymer (C) are/is 50000 or higher.

(6) The resin composition (a) according to any one of (1) to (5), wherein the content of the polymer (A) is 30 to 90% by weight of the total of the resin composition (a).

- 5 (7) A resin composition (b) comprising the following polymers (F), (G) and (H):

(F) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I);

(G) a polymer comprising polystyrene or a polystyrene
10 derivative; and

(H) a graft polymer having a structure where a polymer comprising at least one kind of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene

15 derivative.

(8) The resin composition (b) according to (7), wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (F), (G) and (H).

20 (9) The resin composition (b) according to (7) or (8), wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(10) The resin composition (b) according to any one of (7)
25 to (9), wherein the weight-average molecular weight of the

polymer (F) is 4000 or higher.

(11) The resin composition (b) according to any one of (7) to (10), wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

5 (12) The resin composition (b) according to any one of (7) to (11), wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

(13) A resin composition (c) comprising the following polymers (I) and (J), diphenylsilicone (D), and a phenolic antioxidant

10 (E):

(I) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof; and

15 (J) a polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

(14) The resin composition (c) according to (13), wherein the
20 saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

(15) The resin composition (c) according to (13) or (14), wherein
the content of the heterocyclic structure in the polymer (I)
25 is 0.01 to 5 mol% of the total of the resin composition (c),

and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) is 0.01 to 5 mol% of the total of the resin composition (c).

(16) The resin composition (c) according to any one of (13) to (15), wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

(17) The resin composition (c) according to any one of (13) to (16), wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

(18) The resin composition (c) according to any one of (13) to (17), wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

(19) A molding material obtained by molding a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(20). A sheet obtained from a resin composition selected from the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(21) A film obtained from a resin composition selected from

the resin composition (a) according to (1), the resin composition (b) according to (7) and the resin composition (c) according to (13).

(22) An optical part using the molding material, the sheet
5 or the film according to any one of (19) to (21).

Hereinbelow, the present invention will be described in detail.

<1> The resin composition (a) of the present invention

10 A resin composition (a) of the present invention is a resin composition comprising the following polymers (A), and (B) and/or (C):

(A) a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I) described
15 above;

(B) a polymer comprising polystyrene or a polystyrene derivative; and

(C) a polymer comprising a monomer copolymerizable with styrene or a styrene derivative.

20 In the resin composition (a) of the present invention, the above polymer (A) is not particularly limited and any polymer may be employed as the polymer (A), as long as it may be any polymer containing one or more kinds of indene and indene derivatives represented by the above general formula (I).

25 The indene derivatives for use in the above polymer (A)

5

10

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20

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aromatic hydrocarbon groups are not limited thereto.

X represents a hydrogen atom, a halogen atom, an acyl group, an alkoxy group or a nitrile group. Halogen atoms in X include fluorine, chlorine, bromine, and iodine.

5 Acyl groups in X include formyl group, acetyl group, propionyl group, butyryl group, isobutyryl group, and the like.

Alkoxy groups in X include methoxy group, ethoxy group, propoxy group, butoxy group, pentoxy group, hexoxy group, and the like.

10 Furthermore, x represents 0 or an integer of 1 to 4, and y represents an integer of 1 to 4, where $x + y = 4$.

The above indene or indene derivatives may be used singly or in combination with two or more as a monomer for use in the polymer (A).

15 The above indene derivatives having a substituent include nucleus-substituted alkylindenes such as nucleus-substituted methylindene, nucleus-substituted ethylindene, nucleus-substituted propylindene, nucleus-substituted butylindene and the like,
20 nucleus-substituted chloroindene, nucleus-substituted bromoindene, and the like. More specifically, they preferably include methylindene, α -methylindene, β -methylindene, and the like.

The polymer (B) for use in the resin composition (a)
25 is a polymer comprising polystyrene or a polystyrene derivative.

5 α -substituted alkylstyrenes, β -substituted alkylstyrenes,
nucleus-substituted alkoxytyrenes, and the like.

10 p-ethylstyrene, o-propylstyrene, m-propylstyrene,
p-propylstyrene, o-n-butylstyrene, m-n-butylstyrene,
p-n-butylstyrene, o-isobutylstyrene, m-isobutylstyrene,
p-isobutylstyrene, o-t-butylstyrene, m-t-butylstyrene,
p-t-butylstyrene, o-n-pentylstyrene, m-n-pentylstyrene,
15 p-n-pentylstyrene, o-2-methylbutylstyrene,
m-2-methylbutylstyrene, p-2-methylbutylstyrene,
o-3-methylbutylstyrene, m-3-methylbutylstyrene,
p-3-methylbutylstyrene, o-t-pentylstyrene,
m-t-pentylstyrene, p-t-pentylstyrene, o-n-hexylstyrene,
20 m-n-hexylstyrene, p-n-hexylstyrene, o-2-methylpentylstyrene,
m-2-methylpentylstyrene, p-2-methylpentylstyrene,
o-3-methylpentylstyrene, m-3-methylpentylstyrene,
p-3-methylpentylstyrene, o-1-methylpentylstyrene,
m-1-methylpentylstyrene, p-1-methylpentylstyrene,
25 o-2,2-dimethylbutylstyrene, m-2,2-dimethylbutylstyrene,

p-2,2-dimethylbutylstyrene, o-2,3-dimethylbutylstyrene,
m-2,3-dimethylbutylstyrene, p-2,3-dimethylbutylstyrene,
o-2,4-dimethylbutylstyrene, m-2,4-dimethylbutylstyrene,
p-2,4-dimethylbutylstyrene, o-3,3-dimethylbutylstyrene,
5 m-3,3-dimethylbutylstyrene, p-3,3-dimethylbutylstyrene,
o-3,4-dimethylbutylstyrene, m-3,4-dimethylbutylstyrene,
p-3,4-dimethylbutylstyrene, o-4,4-dimethylbutylstyrene,
m-4,4-dimethylbutylstyrene, p-4,4-dimethylbutylstyrene,
o-2-ethylbutylstyrene, m-2-ethylbutylstyrene,
10 p-2-ethylbutylstyrene, o-1-ethylbutylstyrene,
m-1-ethylbutylstyrene, p-1-ethylbutylstyrene,
o-cyclohexylstyrene, m-cyclohexylstyrene,
p-cyclohexylstyrene, and the like. Those listed hereinbefore
are simply examples, and nucleus-substituted alkylstyrenes
15 are not limited thereto. These may be used singly or in
combination with two or more.

Nucleus-substituted aromatic styrenes that may be
employed include, for example, o-phenylstyrene,
m-phenylstyrene, p-phenylstyrene, and the like. Those listed
20 hereinbefore are simply examples, and nucleus-substituted
aromatic styrenes are not limited thereto.

α -substituted alkylstyrenes that may be employed include,
for example, α -methylstyrene, α -ethylstyrene,
 α -propylstyrene, α -n-butylstyrene, α -isobutylstyrene,
25 α -t-butylstyrene, α -n-pentylstyrene,

α -2-methylbutylstyrene, α -3-methylbutylstyrene,
 α -t-butylstyrene, α -t-pentylstyrene, α -n-hexylstyrene,
 α -2-methylpentylstyrene, α -3-methylpentylstyrene,
 α -1-methylpentylstyrene, α -2,2-dimethylbutylstyrene,
5 α -2,3-dimethylbutylstyrene, α -2,4-dimethylbutylstyrene,
 α -3,3-dimethylbutylstyrene, α -3,4-dimethylbutylstyrene,
 α -4,4-dimethylbutylstyrene, α -2-ethylbutylstyrene,
 α -1-ethylbutylstyrene, α -cyclohexylstyrene, and the like.
Those listed hereinbefore are simply examples, and
10 α -substituted alkylstyrenes are not limited thereto. These
may be used singly or in combination with two or more.

β -substituted alkylstyrenes that may be employed include,
for example, β -methylstyrene, β -ethylstyrene,
 β -propylstyrene, β -n-butylstyrene, β -isobutylstyrene,
15 β -t-butylstyrene, β -n-pentylstyrene, β -2-methylbutylstyrene,
 β -3-methylbutylstyrene, β -t-pentylstyrene, β -n-hexylstyrene,
 β -2-methylpentylstyrene, β -3-methylpentylstyrene,
 β -1-methylpentylstyrene, β -2,2-dimethylbutylstyrene,
 β -2,3-dimethylbutylstyrene, β -2,4-dimethylbutylstyrene,
20 β -3,3-dimethylbutylstyrene, β -3,4-dimethylbutylstyrene,
 β -4,4-dimethylbutylstyrene, β -2-ethylbutylstyrene,
 β -1-ethylbutylstyrene, β -cyclohexylstyrene, and the like.
Those listed hereinbefore are simply examples, and
 β -substituted alkylstyrenes are not limited thereto. These
25 may be used singly or in combination with two or more.

Nucleus-substituted alkoxytyrenes that may be employed include, for example, o-methoxytyrene, m-methoxytyrene, p-methoxytyrene, o-ethoxytyrene, m-ethoxytyrene, p-ethoxytyrene, o-propoxytyrene, m-propoxytyrene, 5 p-propoxytyrene, o-n-butoxytyrene, m-n-butoxytyrene, p-n-butoxytyrene, o-isobutoxytyrene, m-isobutoxytyrene, p-isobutoxytyrene, o-t-butoxytyrene, m-t-butoxytyrene, p-t-butoxytyrene, o-n-pentoxytyrene, m-n-pentoxytyrene, p-n-pentoxytyrene, o-2-methylbutoxytyrene, 10 m-2-methylbutoxytyrene, p-2-methylbutoxytyrene, o-3-methylbutoxytyrene, m-3-methylbutoxytyrene, p-3-methylbutoxytyrene, o-t-pentoxytyrene, m-t-pentoxytyrene, p-t-pentoxytyrene, o-n-hexoxytyrene, m-n-hexoxytyrene, p-n-hexoxytyrene, 15 o-2-methylpentoxytyrene, m-2-methylpentoxytyrene, p-2-methylpentoxytyrene, o-3-methylpentoxytyrene, m-3-methylpentoxytyrene, p-3-methylpentoxytyrene, o-1-methylpentoxytyrene, m-1-methylpentoxytyrene, p-1-methylpentoxytyrene, o-2,2-dimethylbutoxytyrene, 20 m-2,2-dimethylbutoxytyrene, p-2,2-dimethylbutoxytyrene, o-2,3-dimethylbutoxytyrene, m-2,3-dimethylbutoxytyrene, p-2,3-dimethylbutoxytyrene, o-2,4-dimethylbutoxytyrene, m-2,4-dimethylbutoxytyrene, p-2,4-dimethylbutoxytyrene, o-3,3-dimethylbutoxytyrene, m-3,3-dimethylbutoxytyrene, 25 p-3,3-dimethylbutoxytyrene, o-3,4-dimethylbutoxytyrene,

m-3,4-dimethylbutoxystyrene, p-3,4-dimethylbutoxystyrene,
o-4,4-dimethylbutoxystyrene, m-4,4-dimethylbutoxystyrene,
p-4,4-dimethylbutoxystyrene, o-2-ethylbutoxystyrene,
m-2-ethylbutoxystyrene, p-2-ethylbutoxystyrene,
5 o-1-ethylbutoxystyrene, m-1-ethylbutoxystyrene,
p-1-ethylbutoxystyrene, o-cyclohexoxystyrene,
m-cyclohexoxystyrene, p-cyclohexoxystyrene,
o-phenoxy styrene, m-phenoxy styrene, p-phenoxy styrene, and
the like. Those listed hereinbefore are simply examples, and
10 nucleus-substituted alkoxy styrenes are not limited thereto.
These may be used singly or in combination with two or more.

The polymer (C) for use in the resin composition (a)
is a polymer comprising a monomer copolymerizable with styrene
or a styrene derivative. Monomers copolymerizable with
15 styrene or a styrene derivative for use in the polymer (C)
include, for example, styrene, nucleus-substituted
alkylstyrenes, nucleus-substituted aromatic styrenes,
 α -substituted alkylstyrenes, β -substituted alkylstyrenes,
nucleus-substituted alkoxy styrenes, alkyl vinyl ethers,
20 aromatic vinyl ethers, isobutene, diisobutylene,
(meth)acrylic esters having 1 to 8 carbon atoms, and the like.
These may be used singly or in combination with two or more.

Nucleus-substituted alkylstyrenes,
nucleus-substituted aromatic styrenes, α -substituted
25 alkylstyrenes, β -substituted alkylstyrenes, and

nucleus-substituted alkoxystyrenes include the same as listed for the monomers for use in the polymer (B).

Alkyl groups in alkyl vinyl ethers are not particularly limited, and any alkyl group may be employed. Alkyl vinyl ethers include, for example, those having alkyl groups such as methyl, ethyl, propyl, n-butyl, isobutyl, t-butyl, n-pentyl, 2-methylbutyl, 3-methylbutyl, t-pentyl, n-hexyl, 2-methylpentyl, 3-methylpentyl, 4-methylpentyl, 1-methylpentyl, 2,2-dimethylbutyl, 2,3-dimethylbutyl, 2,4-dimethylbutyl, 3,3-dimethylbutyl, 3,4-dimethylbutyl, 4,4-dimethylbutyl, 2-ethylbutyl, 1-ethylbutyl, cyclohexyl, and the like. Those listed hereinbefore are simply examples, and alkyl vinyl ethers are not limited thereto. These may be used singly or in combination with two or more.

Aromatic vinyl ethers include, for example, phenyl vinyl ether and the like. Those listed hereinbefore are simply examples, and aromatic vinyl ethers are not limited thereto.

(Meth)acrylic esters having 1 to 8 carbon atoms include methyl (meth)acrylate, ethyl (meth)acrylate, propyl (meth)acrylate, n-butyl (meth)acrylate, i-butyl (meth)acrylate, n-pentyl (meth)acrylate, n-hexyl (meth)acrylate, n-heptyl (meth)acrylate, n-octyl (meth)acrylate, 2-ethylhexyl (meth)acrylate, and the like. Those listed hereinbefore are simply examples, and (meth)acrylic esters having 1 to 8 carbon atoms are not limited

thereto. These may be used singly or in combination with two or more.

The above styrene, nucleus-substituted alkylstyrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxytyrenes, alkyl vinyl ethers, aromatic vinyl ethers, isobutene, diisobutylene, (meth)acrylic esters having 1 to 8 carbon atoms, and the like for use in the polymer (C) may have a substituent such as an alkyl group, a phenyl group, a halogen atom and the like at an optional position.

Methods of the production of the above polymers (A), (B) and (C) in the resin composition (a) of the present invention are not particularly limited, and the polymers can be produced by a conventional method. For example, they can be produced by cationic polymerization, anionic polymerization, radical polymerization, living radical polymerization, or the like. The above polymerization methods can be selected depending on a catalyst employed.

Catalysts for use in cationic polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts that may be employed include, for example, Lewis acids such as aluminium chloride, iron chloride, tin chloride, zinc chloride, strontium chloride, scandium chloride and the like, proton acids such as sulfuric acid, para-toluenesulfonic acid, hydrochloric acid, nitric acid and

the like, alkylaluminum chlorides, and the like. Those listed hereinbefore are simply examples, and the catalysts are not limited thereto. These may be used singly or in combination with two or more.

5 Catalysts for use in anionic polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts that may be employed include, for example, butyllithium and the like. Those listed hereinbefore are simply examples, and the catalysts are not limited thereto.

10 Catalysts for use in radical polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts include, for example, peroxides such as benzoyl peroxide, lauryl peroxide, methyl ethyl ketone peroxide and the like. Those listed hereinbefore are simply
15 examples, and the catalysts are not limited thereto. These may be used singly or in combination with two or more.

 Catalysts for use in living radical polymerization are not particularly limited, and publicly known catalysts may be employed. Such catalysts include, for example, a combined
20 system of benzoyl peroxide and a nitroxide compound, a combined system of a Ru complex/an alkoxyaluminum and the like. Those listed hereinbefore are simply examples, and the catalysts are not limited thereto. These may be used singly or in combination with two or more.

25 With respect to polymerization methods, the polymers

can be synthesized by solution polymerization, suspension polymerization, bulk polymerization, or the like. In particular, the solution polymerization method is the most preferable.

5 Solvents employed are not particularly limited, and publicly known solvents may be employed. Typical solvents include, for example, chloromethane, dichloromethane, trichloromethane, tetrachloromethane, chloroethane, dichloroethane, trichloroethane, tetrachloroethane,
10 chloroethylene, dichloroethylene, nitrobenzene, dinitrobenzene, trinitrobenzene, alkylbenzenes such as methylbenzene, dimethylbenzene, trimethylbenzene, ethylbenzene, diethylbenzene, triethylbenzene and the like, ketones such as acetone, methyl ethyl ketone, methyl isobutyl
15 ketone and the like, and esters such as MMA, ethyl acetate, butyl acetate and the like. Those listed hereinbefore are simply examples, and the solvents are not limited thereto. These may be used singly or in combination with two or more.

 The polymerization temperature is preferably in the
20 range of -100 to 180°C . If the polymerization reaction is carried out at a lower temperature than -100°C , decrease in reactivity is caused, so that it is difficult to obtain a sufficiently high molecular weight compound. The temperatures exceeding 180°C lead to too high reactivity of
25 the propagation terminal, so that it sometimes becomes to be

difficult to obtain a high molecular weight compound because a vast number of chain transfer reactions occur.

In the resin composition (a), the weight-average molecular weight of the polymer (A) is preferably lower than 80000, more preferably lower than 40000. If the weight-average molecular weight of the polymer (A) is lower than 80000, fluidity and transparency of the resin composition (a) tend to decrease.

To make the weight-average molecular weight of the polymer (A) within the above range, the molecular weight can be adjusted by selecting the kind or amount of the catalyst used in polymerization, using a polymerization inhibitor, using a chain transfer agent, controlling the polymerization temperature or the like.

Furthermore, the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is preferably 50000 or higher, more preferably 100000 or higher. If the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) are/is lower than 50000, strength of a molding material tends to decrease.

To make the weight-average molecular weight(s) of the polymer (B) and/or the polymer (C) within the above range, the molecular weight(s) can be adjusted by selecting the kind or amount of the catalyst used in polymerization, using a polymerization inhibitor, using a chain transfer agent, controlling the polymerization temperature or the like.

Weight-average molecular weights can be determined by GPC measurement with a tetrahydrofuran solution.

The polymers (A), (B) and (C) obtained by the above method can be used for the resin composition (a) after isolating the
5 polymers by a conventional method.

In the present invention, the content of the polymer (A) is preferably 30 to 90% by weight of the total of the resin composition (a), more preferably 50 to 90% by weight, still more preferably 60 to 85% by weight. If the content of the
10 polymer (A) is less than 30% by weight or more than 90% by weight of the total of the resin composition (a), the absolute value of birefringence tends to increase.

Moreover, it is preferred to add a diphenylsilicone (D) and/or a phenolic antioxidant (E) to the resin composition
15 (a).

Viscosity of the diphenylsilicone (D) for use in the resin composition (a) of the present invention is not particularly limited, and any diphenylsilicone (D) having any viscosity may be used. The addition amount of the
20 diphenylsilicone (D) is preferably in the range of 0.01 to 1.0% by weight, more preferably 0.05 to 0.8% by weight of the total of the resin composition (a). If the addition amount is less than 0.01% by weight, the effect on mold release characteristics from a die in injection molding tends to
25 decrease, while if the addition amount exceeds 1.0% by weight,

heat resistance tends to decrease.

Phenolic antioxidants (E) for use in the present invention include, for example, dibutylhydroxytoluene, alkylated phenols, 4,4'-thiobis(6-t-butyl-3-methylphenol),
5 4,4'-butylidenebis(6-t-butyl-3-methylphenol),
2,2''-methylenebis(4-methyl-6-t-butylphenol),
2,2''-methylenebis(4-ethyl-6-t-butylphenol),
2,6-di-t-butyl-4-ethylphenol,
1,1,-tris(2-methyl-4-hydroxy-5-t-butylphenyl)butane,
10 n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate,
tetrakis(methylene-3-(3,5-di-t-butyl-4-hydroxyphenyl)propionate, dilaurylthiodipropionate, distearylthiodipropionate, dimyristylthiodipropionate, and the like, and the phenolic antioxidants are not limited thereto. These may be used singly
15 or in combination with two or more. The addition amount of a phenolic antioxidant (E) is preferably in the range of 0.1 to 3.0% by weight, more preferably 0.5 to 2.0% by weight of the total of the resin composition (a). If the addition amount is less than 0.1% by weight, the effect to suppress changes
20 in hue is a little, while if the addition amount exceeds 3.0% by weight, transparency and heat resistance of the resin tend to decrease.

Methods of mixing the polymers (A), and (B) and/or (C), a diphenylsilicone (D), and a phenolic antioxidant (E) are
25 not particularly limited, and a resin composition can be

produced by weighing out prescribed amounts of each polymer and a diphenylsilicone and a phenolic antioxidant, and melt-kneading these, or also can be produced by dissolving each polymer, a diphenylsilicone and a phenolic antioxidant
5 in a solvent such as toluene, THF, NMP and the like, and then removing the solvent.

The resin composition (a) of the present invention obtained as mentioned above preferably has a saturated water absorption of 0.4% or less, and preferably has a birefringence
10 in stretching the resin composition by 200% in the range of -2×10^{-6} to 2×10^{-6} . More preferable saturated water absorption is 0.2% or less, and more preferable birefringence in stretching the resin composition by 200% is in the range of -1×10^{-6} to 1×10^{-6} .

15 Saturated water absorptions exceeding 0.4% lead to an increased change in refraction index in absorbing water, thus it is not preferable. Moreover, if the birefringence in stretching the resin composition by 200% is out of the range of -2×10^{-6} to 2×10^{-6} , it is not preferable because linearly
20 polarized light sometimes greatly changes to elliptically polarized light.

To make the saturated water absorption within the above range, it is satisfactory to make the content of the polymer (A) within the range of 30 to 90% by weight of the total of
25 the resin composition (a).

To make the birefringence in stretching the resin composition by 200% within the above range, it is satisfactory to make the content of the polymer (A) within the range of 30 to 90% by weight of the total of the resin composition (a).

5 The saturated water absorption (%) in the present invention can be calculated by measuring the water absorption when the water absorption reaches saturation with a sample fragment soaked in hot water at 70°C. "When the water absorption reaches saturation" is the state in which there
10 is no more change in the water absorption even if the sample fragment is allowed to be soaked in hot water at 70°C for a longer time.

Furthermore, concerning birefringence, the birefringence in stretching an obtained molding material by
15 200% at a temperature 5°C lower than the glass transition point of the material can be measured by using, for example, Ellipsometer AEP-100 Type (produced by Shimadzu Corporation). Measurement conditions are as follows: temperature: 25°C; and wavelength of the laser light: 632.8 nm. Moreover, the glass
20 transition point of a molding material can be measured as follows. The glass transition point can be measured by DSC (differential scanning calorimetry). A measurement by DSC is carried out under a condition of a temperature-elevating rate of 10°C/min.

25 <2> The resin composition (b) of the present invention

A resin composition (b) of the present invention is a resin composition comprising the following polymers (F), (G) and (H):

(F) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I);

(G) a polymer comprising polystyrene or a polystyrene derivative; and

(H) a graft polymer having a structure where a polymer comprising at least one kind of indene and an indene derivative represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative.

The polymer (F) for use in the resin composition (b) can be produced in the same manner as the polymer (A) for use in the resin composition (a) by using the same indene monomers as in the polymer (A). The weight-average molecular weight of the polymer (F) is preferably 4000 or higher, more preferably 8000 or higher. If the weight-average molecular weight of the polymer (F) is lower than 4000, heat resistance tends to decrease.

To make the weight-average molecular weight of the polymer (F) within the above range, the molecular weight can be adjusted by selecting the kind or amount of the catalyst used in polymerization, using a polymerization inhibitor, using a chain transfer agent, controlling the polymerization

temperature or the like.

Furthermore, the polymer (G) for use in the resin composition (b) can be produced in the same manner as the polymer (B) for use in the resin composition (a) by using the same
5 styrene monomers as in the polymer (B).

The graft polymer (H) for use in the resin composition (b) has a structure where a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I) bonds to a side chain of a polymer comprising
10 styrene or a styrene derivative. That is, the graft polymer (H) has a backbone unit of the polymer comprising styrene or a styrene derivative and branch units of the polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I).

15 Monomers copolymerizable with styrene or a styrene derivative for use in a constitutional monomer of the backbone unit of the graft polymer (H) include, for example, styrene, nucleus-substituted alkylstyrenes, nucleus-substituted aromatic styrenes, α -substituted alkylstyrenes,
20 β -substituted alkylstyrenes, nucleus-substituted alkoxy styrenes, alkyl vinyl ethers, aromatic vinyl ethers, isobutene, diisobutylene, (meth)acrylic esters having 1 to 8 carbon atoms, and the like.

Nucleus-substituted alkylstyrenes,
25 nucleus-substituted aromatic styrenes, α -substituted

alkylstyrenes, β -substituted alkylstyrenes, and nucleus-substituted alkoxytyrenes include the same as listed for the monomers for use in the polymer (B) of the resin composition (a). Furthermore, alkyl vinyl ethers, aromatic vinyl ethers, and (meth)acrylic esters having 1 to 8 carbon atoms include the same as listed for the monomers for use in the polymer (C) of the resin composition (a).

The above styrene, nucleus-substituted alkylstyrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxytyrenes, alkyl vinyl ethers, aromatic vinyl ethers, isobutene, diisobutylene, (meth)acrylic esters having 1 to 8 carbon atoms, and the like for use in the graft polymer (H) may have a substituent such as an alkyl group, a benzene ring, a halogen atom at an optional position.

Indene or indene derivatives for use in a constitutional monomer of a branched unit of the graft polymer (H) include those represented by the general formula (I) as mentioned above.

In the resin composition (b) of the present invention, methods for the production of the above graft polymer (H) include conventional methods for the production of a graft polymer, and, for example, there is a method as follows.

The method comprises dissolving a polymer which was produced beforehand by radical polymerization of a monomer copolymerizable with styrene or a styrene derivative, etc.,

in toluene, THF, NMP or the like, further dissolving indene or an indene derivative represented by the general formula (I), thereafter adding a Lewis acid such as tin chloride, aluminum chloride and the like as a catalyst and
5 2,6-bis(t-butyl)pyridine and the like as an assist catalyst, and conducting cationic polymerization.

Furthermore, the weight-average molecular weight of the backbone unit of the graft polymer (H) is preferably 10000 or higher.

10 Furthermore, the weight-average molecular weights of the polymer (G) and the graft polymer (H) are preferably 50000 or higher, more preferably 100000 or higher. If the weight-average molecular weights of the polymer (G) and the graft polymer (H) are lower than 50000, strength of a molding
15 material tends to decrease.

To make the weight-average molecular weights of the polymer (G) and the graft polymer (H) within the above range, the molecular weight can be adjusted by selecting the kind or amount of the catalyst used in polymerization, using a
20 polymerization inhibitor, using a chain transfer agent, controlling the polymerization temperature or the like.

Moreover, it is preferred to add a diphenylsilicone and/or a phenolic antioxidant to the resin composition (b).

Similarly to the diphenylsilicone (D) for use in the
25 resin composition (a), viscosity of the diphenylsilicone (D)

for use in the resin composition (b) of the present invention is not particularly limited, and any diphenylsilicone (D) having any viscosity may be used. The addition amount of the diphenylsilicone (D) is preferably in the range of 0.01 to 1.0% by weight, more preferably 0.05 to 0.8% by weight of the total of the resin composition (b). If the addition amount is less than 0.01% by weight, the effect on mold release characteristics from a die in injection molding tends to decrease, while if the addition amount exceeds 1.0% by weight, heat resistance tends to decrease.

Phenolic antioxidants for use in the resin composition (b) of the present invention include phenolic antioxidants (E) for use in the resin composition (a). The addition amount of a phenolic antioxidant is not particularly limited, and is preferably in the range of 0.1 to 3.0% by weight, more preferably 0.5 to 2.0% by weight of the total of the resin composition (b). If the addition amount of a phenolic antioxidant (E) is less than 0.1% by weight, the effect to suppress changes in hue is a little, while if the addition amount exceeds 3.0% by weight, transparency and heat resistance of the resin tend to decrease.

Methods of mixing the polymers (F), (G) and (H) obtained by the above methods, a diphenylsilicone (D), and a phenolic antioxidant (E) are not particularly limited, and the same methods as in the above resin composition (a) may be used.

In the resin composition (b) of the present invention, the content of the polymer (F) is preferably 30 to 90% by weight of the total of the resin composition (b), more preferably 50 to 90% by weight, still more preferably 60 to 85% by weight.

- 5 If the content of the polymer (F) is less than 30% by weight or more than 90% by weight of the total of the resin composition (b), the absolute value of birefringence tends to increase.

The resin composition (b) of the present invention obtained as mentioned above preferably has a saturated water
10 absorption of 0.4% or less, and preferably has a birefringence in stretching the resin composition by 200% in the range of -2×10^{-6} to 2×10^{-6} . More preferable saturated water absorption is 0.2% or less, and more preferable birefringence in stretching the resin composition by 200% is in the range of -1×10^{-6} to
15 1×10^{-6} .

Saturated water absorptions exceeding 0.4% lead to an increased change in refraction index in absorbing water, thus it is not preferable. Moreover, if the birefringence in stretching the resin composition by 200% is out of the range
20 of -2×10^{-6} to 2×10^{-6} , it is not preferable because linearly polarized light sometimes greatly changes to elliptically polarized light.

To make the saturated water absorption within the above range, it is satisfactory to make the content of the polymer
25 (F) within the range of 30 to 90% by weight of the total of

the resin composition.

To make the birefringence in stretching the resin composition by 200% within the above range, it is satisfactory to make the content of the polymer (F) within the range of
5 30 to 90% by weight of the total of the resin composition.

<3> The resin composition (c) of the present invention

A resin composition (c) of the present invention is a resin composition comprising the following polymers (I) and
10 (J), diphenylsilicone (D), and a phenolic antioxidant (E):
(I) a polymer comprising one or more kinds of indene and indene derivatives represented by the above general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof; and
15 (J) a polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

As indene monomers for use in the polymer (I), the same
20 indene monomers as in the polymer (A) for use in the resin composition (a) may be used.

Methods for introducing a heterocyclic structure into a side chain of the polymer (I) are not particularly limited, and the following method is an example.

25 [1] After producing a polymer that comprises the above indene

or an indene derivative and has functional groups, the polymer (I) having a heterocyclic structure in a side chain thereof is produced by reacting the above produced polymer with a compound having a heterocyclic structure.

5 Specifically, in the case of introducing a heterocyclic structure into a side chain of the polymer (I), for example, a copolymer having acid anhydride moieties as functional groups can be obtained by synthesizing a polymer of the above indene or an indene derivative and a vinyl monomer having an acid
10 anhydride moiety, such as maleic anhydride. Then, a heterocyclic structure can be introduced into a side chain by ring-opening the acid anhydride moiety of maleic anhydride with an amino group of a compound having an amino group and a heterocyclic structure, such as aminopyridine.

15 [2] The polymer (I) having a heterocyclic structure in a side chain thereof is produced by copolymerizing a monomer having a heterocyclic structure with reaction activity with a monomer copolymerizable with indene or an indene derivative by a conventional method.

20 Monomers having a heterocyclic structure with reaction activity for use in the above [2] include, for example, pyridine, imidazoline, pyrazine, pyrimidine, quinoline, indolizine, acridine, furan, thiophene, oxazole and the like, each of which has a polymerizable reactive group. Specifically,
25 vinylpyridine, pyridyl vinyl ether, pyridylmaleimide and the

like may be used, and the monomers are not limited thereto. Furthermore, these may be used singly or in combination with two or more.

In the resin composition (c) of the present invention,
the above polymer (J) comprises a monomer copolymerizable with
styrene or a styrene derivative, and it has a carboxyl group
and/or a phenolic hydroxyl group in a side chain thereof.

Monomers copolymerizable with styrene or a styrene derivative for use in the polymer (J) include, for example, nucleus-substituted alkylstyrenes, nucleus-substituted aromatic styrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxy styrenes, alkyl vinyl ethers, aromatic vinyl ethers, and the like, and specifically include the same monomers as the styrene monomers for use in the polymer (B) of the resin composition (a).

Furthermore, monomers copolymerizable with a styrene derivative for use in the polymer (J) include, for example, nucleus-substituted alkylstyrenes, nucleus-substituted aromatic styrenes, α -substituted alkylstyrenes, β -substituted alkylstyrenes, nucleus-substituted alkoxy styrenes, alkyl vinyl ethers, aromatic vinyl ethers, isobutene, diisobutylene, (meth)acrylic esters having 1 to 8 carbon atoms, and the like, and specifically include the same monomers as the monomers for use in the polymer (C) of

the resin composition (c).

Methods for introducing a carboxyl group and/or a phenolic hydroxyl group into a side chain of the polymer (J) are not particularly limited, and the following method is an example.

[1] After producing a polymer that comprises one or more kinds of the above styrene and styrene derivatives and has functional groups, the polymer (J) having a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof is produced by reacting the above produced polymer with a compound having a carboxyl group or a phenolic hydroxyl group.

Specifically, in the case of introducing a carboxyl group into a side chain of the polymer (J), for example, a copolymer having alcoholic hydroxyl groups as functional groups can be obtained by synthesizing a copolymer of the above styrene or styrene derivative and a vinyl monomer having an alcoholic hydroxyl group, such as 2-hydroxyethyl methacrylate (HEMA). Then, a carboxyl group can be introduced into a side chain by conducting a ring-opening addition of an acid anhydride such as trimellitic anhydride to an alcoholic hydroxyl group of HEMA.

Furthermore, in the case of introducing a phenolic hydroxyl group into a side chain of the polymer (J), a polymer having acid anhydride moieties as functional groups can be obtained by synthesizing a polymer of the above styrene or

styrene derivative and a vinyl monomer having an acid anhydride moiety, such as maleic anhydride. Then, a phenolic hydroxyl group can be introduced into a side chain by ring-opening the acid anhydride moiety of maleic anhydride with an amino group of a compound having an amino group and a phenolic hydroxyl group, such as aminophenol.

[2] The polymer (J) having a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof is produced by copolymerizing a monomer having a carboxyl group or a phenolic hydroxyl group with reaction activity with the above styrene or styrene derivatives by a conventional method.

Monomers having a carboxyl group or a phenolic hydroxyl group with reaction activity for use in the above [2] include, for example, methacrylic acid, acrylic acid, maleic acid, vinylphenol, vinylbenzoic acid and the like, and the monomers are not limited thereto. Furthermore, these may be used singly or in combination with two or more.

In the resin composition (c) of the present invention, the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), more preferably 0.02 to 2 mol%. If the content of the heterocyclic structure is less than 0.01 mol%, transparency of the resin composition (c) tends to decrease, while if the content exceeds 5 mol%, water absorption of the resin composition tends to increase.

The content(s) of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) are/is 0.01 to 5 mol% of the total of the resin composition (c), more preferably 0.02 to 2 mol%. If the content(s) of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) are/is less than 0.01 mol%, transparency of the resin composition (c) tends to decrease, while if the content exceeds 5 mol%, water absorption of the resin composition (c) tends to increase.

In the present invention, the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is preferably 0.1 to 10.0. If this ratio is less than 0.1 or exceeds 10.0, transparency of the resin composition (c) tends to decrease.

Methods of the production of the above polymers (I) and (J) are not particularly limited in the present invention, and the polymers can be produced by a conventional method using the above-mentioned monomers.

Similarly to the diphenylsilicone (D) for use in the resin composition (a), viscosity of the diphenylsilicone (D) for use in the resin composition (c) of the present invention is not particularly limited, and any diphenylsilicone (D) having any viscosity may be used. The addition amount of the diphenylsilicone (D) is preferably in the range of 0.01 to 1.0% by weight, more preferably 0.05 to 0.8% by weight of the total of the resin composition (c). If the addition amount

is less than 0.01% by weight, the effect on mold release characteristics from a die in injection molding tends to decrease, while if the addition amount exceeds 1.0% by weight, heat resistance tends to decrease.

5 Phenolic antioxidants for use in the resin composition (c) of the present invention include phenolic antioxidants (E) for use in the resin composition (a). The addition amount of a phenolic antioxidant is not particularly limited, and is preferably in the range of 0.1 to 3.0% by weight, more
10 preferably 0.5 to 2.0% by weight of the total of the resin composition (c). If the addition amount of a phenolic antioxidant (E) is less than 0.1% by weight, the effect to suppress changes in hue is a little, while if the addition amount exceeds 3.0% by weight, transparency and heat resistance
15 of the resin tend to decrease.

Methods of mixing the polymers (I) and (J) obtained by the above methods, a diphenylsilicone (D), and a phenolic antioxidant (E) are not particularly limited, and the same methods as in the above resin composition (a) may be used.

20 In the resin composition (c) of the present invention, the content of the polymer (I) is preferably 30 to 90% by weight of the total of the resin composition (c), more preferably 50 to 90% by weight, still more preferably 60 to 85% by weight. If the content of the polymer (I) is less than 30% by weight
25 or more than 90% by weight of the total of the resin composition

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10 Saturated water absorptions exceeding 0.4% lead to an increased change in refraction index in absorbing water, thus it is not preferable. Moreover, if the birefringence in stretching the resin composition by 200% is out of the range of -2×10^{-6} to 2×10^{-6} , it is not preferable because linearly
15 polarized light sometimes greatly changes to elliptically polarized light.

To make the birefringence in stretching the resin composition by 200% within the above range, it is satisfactory to make the content of the polymer (I) within the range of

30 to 90% by weight of the total of the resin composition (c).

<4> The molding material of the present invention

The above resin composition (a), resin composition (b)
5 and resin composition (c) according to the present invention
can be processed to obtain a molding material, a sheet or a
film. In the present invention, optional components may be
added when required in making these resin compositions into
molding materials.

10 The resin compositions of the present invention may be
applied to semiconductor-related materials that can satisfy
the characteristics such as low permittivity, low
hygroscopicity and high heat resistance, or to optical parts,
as well as paints, photosensitive materials, adhesives, sewage
15 disposal agents, heavy metal collectors, ion-exchange resins,
antistatic agents, antioxidants, anti-fog agents,
anti-corrosive agents, reverse printing agents,
anti-microbial agents, insecticides, medical materials,
coagulants, surfactants, lubricants, binders for solid fuel,
20 conductivity imparting agents, and the like.

Optical parts using a molding material of the present
invention include pickup lenses for CD, pickup lenses for DVD,
lenses for facsimile, lenses for LBP, polygon mirrors, prisms,
and the like.

BEST MODE FOR CARRYING OUT THE INVENTION

The present invention is described in further detail with reference to some examples. However, the present
5 invention should not be construed as being limited to these examples.

Evaluation methods used in the examples are as follows.

(1) Weight-average molecular weight

The weight-average molecular weight of a polymer
10 synthesized was determined by GPC measurement with a tetrahydrofuran solution.

(2) Fluidity (MI)

The fluidity of a resin composition was determined by measuring a melt flow rate at 220°C with a load of 5 kgf.

15 (3) Saturated water absorption

The saturated water absorption of a sample was determined by measuring the water absorption when the water absorption reaches saturation with a sample soaked in hot water at 70°C. Water absorption in Table 1 shows the saturated water
20 absorption.

(4) Heat resistance (Tg)

The heat resistance was evaluated by measuring the glass transition point by DSC (differential scanning calorimetry). The measurement of DSC was carried out under a condition of
25 a rate of temperature rise of 10°C/min.

(5) Relative permittivity

The relative permittivity was measured by using precision LCR meter 4284A Type produced by Hewlett-Packard Company under conditions of 20 kV, 1 kHz and 25°C.

5 (6) Bending strength

The bending strength of a sample fragment was measured by using AGS-1000G produced by Shimadzu Corporation. The test was carried out at room temperature under conditions of a test speed of 0.5 mm/min., a span of 20 mm and the width of the
10 sample fragment of 10 mm.

(7) Transparency

The transparency of a formed sample was measured by using V-570 produced by JASCO Corporation at 25°C. The transparency measured at measurement wavelengths in the range of 400 to
15 800 nm was assumed to be the total light ray transparency.

(8) Birefringence

The birefringence of an obtained molding material stretched by 150% at a temperature 5°C lower than the glass transition temperature of the material was measured. The
20 measurement was carried out by using Ellipsometer AEP-100 Type produced by Shimadzu Corporation at 25°C. The wavelength of the laser beam was 632.8 nm.

(9) Change in hue

After a resin was allowed to abide in an injection molding
25 machine at 250°C for 30 minutes, injection molding was carried

out, and then the change in hue of the molding product thus obtained was measured with a spectrophotometer (produced by Sakata Ink Corporation, Macbeth color-eye 7000A).

(10) Mold release characteristics

- 5 With respect to the mold release characteristics in injection molding, injection molding of a resin was actually carried out, and the surface condition of the resin mold-released from a die and whether the resin was broken or not were visually confirmed.

10

EXAMPLE 1

- Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of toluene, and 0.05 g of FeCl_3 was added thereto at 25°C, thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 2200.

- Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate

25

were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours
5 to obtain a polymer (B). The weight-average molecular weight of the polymer obtained was 200000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (A) and 4.0 g of the polymer (B), and the mixture was added to about 300 g of methanol to precipitate a solid. This solid
10 was dried at 40°C for 6 hours to obtain a desired white precipitate. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample
15 fragment. The evaluation results are shown in Table 1.

EXAMPLE 2

Placed in a 100-mL flask were 8.0 g of indene, 2.0 g
20 of 4-methylstyrene and 30.0 g of methylene chloride, and 0.05 g of FeCl₃ was added thereto at -40°C, thereby being allowed to react for 12 hours. Thereafter 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution
25 thus obtained was gradually added to 100 g of methanol to obtain

9.8 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 15000.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1
5 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. After reaction was allowed for a predetermined time, a granular polymer was
10 isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (B). The weight-average molecular weight of the polymer obtained was 200000.

Placed in a 100-mL flask were 14.0 g of styrene, 5.0
15 g of 4-methylstyrene, 1.0 g of butyl acrylate and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. The reaction was allowed
20 for a predetermined time. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (C). The weight-average molecular weight of the polymer obtained was 240000.

25 Dissolved in 20 g of toluene were 6.0 g of the polymer

(A), 1.5 g of the polymer (B) and 2.5 g of the polymer (C), and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired white precipitate. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The evaluation results obtained by evaluating this sample fragment in the same manner as in Example 1 are shown in Table 1.

10

EXAMPLE 3

Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of toluene, and 0.05 g of FeCl_3 was added thereto at 25°C, thereby being allowed to react for 12 hours. Thereafter 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 2200.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate

25

were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (B). The weight-average molecular weight of the polymer obtained was 200000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (A) and 4.0 g of the polymer (B), 0.01 g of diphenylsilicone (produced by Shin-Etsu Chemical Co., Ltd.) having a viscosity of 500 CS and 0.05 g of n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate, and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 1.

20 EXAMPLE 4

Placed in a 100-mL flask were 8.0 g of indene, 2.0 g of 4-methylstyrene and 30.0 g of methylene chloride, and 0.05 g of FeCl₃ was added thereto at -40°C, thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was

added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.8 g of a white precipitate. This white precipitate
5 was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 15000.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate
10 were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (B). The weight-average molecular weight
15 of the polymer obtained was 200000.

Placed in a 100-mL flask were 14.0 g of styrene, 5.0 g of 4-methylstyrene, 1.0 g of butyl acrylate and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate
20 were added thereto, and the mixture was allowed to react at 70°C for 12 hours with stirring. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (B). The weight-average molecular weight
25 of the polymer obtained was 240000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (A), 1.5 g of the polymer (B), 2.5 g of the polymer (C), 0.01 g of diphenylsilicone having a viscosity of 500 CS and 0.05 g of n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl) propionate, and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 1.

Table 1

Item	unit	Example 1		Example 2			Example 3		Example 4		
		Polymer A	Polymer B	Polymer A	Polymer B	Polymer C	Polymer A	Polymer B	Polymer A	Polymer B	Polymer C
Molecular weight (M _w)	g/mol	2200	200000	15000	200000	240000	2200	200000	15000	200000	240000
Mixing ratio	% by weight	60	40	60	15	25	60	40	60	15	25
Antioxidant E	% by weight	0		0			0.5		0.5		
Silicone amount D	% by weight	0		0			0.1		0.1		
Fluidity (MI)	g/10 minutes	21		12			21		12		
Water absorption	%	0.09		0.08			0.09		0.08		
Heat resistance (T _g)	°C	135		142			135		142		
Relative permittivity	-	2.3		2.2			2.3		2.2		
Bending strength	MPa	80		85			80		85		
Transparency	%	85		85			85		85		
Birefringence	-	1×10^{-6}		1×10^{-5}			1×10^{-6}		1×10^{-6}		
Change in hue	-	0.28		0.29			0.12		0.15		

COMPARATIVE EXAMPLE 1

Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of toluene, and 0.05 g of FeCl_3 was added thereto at 25°C ,
5 thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate.
10 This white precipitate was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 2200.

Next, placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred
15 to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about
20 2 hours to obtain a polymer (B). The weight-average molecular weight of the polymer obtained was 200000.

Dissolved in 20 g of toluene were 4.0 g of the polymer (A) and 6.0 g of the polymer (B), and the mixture was added to about 300 g of methanol to precipitate a solid. This solid
25 was dried at 40°C for 6 hours to obtain a desired white

precipitate. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample
5 fragment. The evaluation results are shown in Table 2.

COMPARATIVE EXAMPLE 2

Placed in a 100-mL flask were 10.0 g of indene and 30.0
10 g of nitrobenzene, and 0.05 g of FeCl_3 was added thereto at 0°C , thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added
15 to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (A). The weight-average molecular weight of this polymer was 7500.

Next, placed in a 100-mL flask were 20.0 g of styrene
20 and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric
25 acid. Subsequently, the polymer was dried at 50°C for about

2 hours to obtain a polymer (B). The weight-average molecular weight of the polymer obtained was 200000.

Dissolved in 20 g of toluene were 9.5 g of the polymer (A) and 0.5 g of the polymer (B), and the mixture was added
5 to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a white precipitate of a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment.
10 The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 2.

Table 2

item	unit	Comparative Example 1		Comparative Example 2	
		Polymer A	Polymer B	Polymer A	Polymer B
Molecular weight (Mw)	g/mol	2200	200000	7500	200000
Mixing ratio	% by weight	40	60	95	5
Antioxidant E	% by weight	0		0	
Silicone amount D	% by weight	0		0	
Fluidity (MI)	g/10 minutes	13		12	
Water absorption	%	0.10		0.08	
Heat resistance (Tg)	°C	121		142	
Relative permittivity	-	2.3		2.3	
Bending strength	Mpa	80		48	
Transparency	%	85		85	
Birefringence	-	5×10^{-5}		Could not be measured	
Change in hue	-	0.28		0.29	

EXAMPLE 5

Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of nitrobenzene, and 0.05 g of FeCl_3 was added thereto at 0°C, thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (F). The weight-average molecular weight of this polymer was 7500.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (G). The weight-average molecular weight of the polymer obtained was 200000.

In advance, 18.0 g of styrene, 2.0 g of p-chloromethylstyrene and 0.1 g of benzoyl peroxide were placed in a 100-mL flask, the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.1 g of calcium phosphate were

added thereto, and the mixture was allowed to react at 70°C for 12 hours with stirring. Thereafter a granular polymer was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours. Dissolved
5 in 30 g of toluene was 6.0 g of the granular polymer thus obtained, and 4.0 g of indene was further added thereto, and the mixture was stirred until the mixture became homogeneous. After that, 0.003 g of 2,6-bis(t-butyl)pyridine was added at 25°C and dissolved. Then, 0.03 g of tin chloride was added, and the
10 mixture was allowed to stand for 24 hours to obtain a graft polymer (H). After 0.05 g of methanol was added to the reaction mixture liquid thus obtained, this reaction mixture liquid was poured in methanol in an amount about 10 times that of the reaction mixture liquid of methanol, and a polymer thus
15 formed was isolated. This polymer was dried at 40°C for 6 hours to obtain 9.8 g of a polymer (H). The weight-average molecular weight of this polymer was 210000.

Dissolved in 20 g of toluene were 5.5 g of the polymer (F), 3.5 g of the polymer (G), and 1.0 g of the polymer (H),
20 and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a white precipitate of a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material
25 was used as a sample fragment. The above-mentioned evaluations

were carried out using this sample fragment. The evaluation results are shown in Table 3.

EXAMPLE 6

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Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of nitrobenzene, and 0.05 g of FeCl_3 was added thereto at 0°C , thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (F). The weight-average molecular weight of this polymer was 7500.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (G). The weight-average molecular weight of the polymer obtained was 200000.

25 In advance, 18.0 g of styrene, 2.0 g of

p-chloromethylstyrene and 0.1 g of benzoyl peroxide were placed in a 100-mL flask, the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.1 g of calcium phosphate were added thereto, and the mixture was allowed to react at 70°C for 12 hours with being stirred. After the reaction was allowed for a predetermined time, the granular polymer was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours. Dissolved in 30 g of toluene was 6.0 g of the granular polymer thus obtained, and 4.0 g of indene was further added thereto, and the mixture was stirred until the mixture became homogeneous. After that, 0.003 g of 2,6-bis(t-butyl)pyridine was added at 25°C and dissolved. Then, 0.03 g of tin chloride was added, and the mixture was allowed to stand for 24 hours to obtain a graft polymer. After 0.05 g of methanol was added to the reaction mixture liquid, this reaction mixture liquid was poured in methanol in about 10 times the amount of the reaction mixture liquid of methanol, and a polymer thus formed was isolated. This polymer was dried at 40°C for 6 hours to obtain 9.8 g of a polymer (H). The weight-average molecular weight of this polymer was 210000.

Dissolved in 20 g of toluene were 5.5 g of the polymer (F), 3.5 g of the polymer (G), 1.0 g of the polymer (H), 0.01 g of diphenylsilicone (produced by Shin-Etsu Chemical Co., Ltd.) having a viscosity of 500 CS and 0.05 g of

n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate, and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a white precipitate of a desired resin composition.

5 This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 3.

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EXAMPLE 7

Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of toluene, and 0.01 g of $AlCl_3$ was added thereto at 25°C, thereby being allowed to react for 6 hours. Thereafter 0.01 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.8 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (F). The weight-average molecular weight of this polymer was 10000.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate

were added to the monomer mixture, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated to obtain a polymer (G). The weight-average molecular weight of the polymer obtained
5 was 200000.

In advance, 18.0 g of styrene, 2.0 g of p-chloromethylstyrene and 0.1 g of benzoyl peroxide were placed in a 100-mL flask, the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were
10 added to the monomer mixture, and the mixture was allowed to react at 70°C for 12 hours with bring stirred. The granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours. Dissolved in 30 g of toluene was 6.0 g of the granular
15 polymer thus obtained, and 4.0 g of indene was further added thereto, and the mixture was stirred until the mixture became homogeneous. After that, 0.003 g of 2,6-bis(t-butyl)pyridine was added at 25°C and dissolved. Then, 0.03 g of tin chloride was added, and the mixture was allowed to stand for 24 hours
20 to obtain a graft polymer. After 0.05 g of methanol was added to the reaction mixture liquid thus obtained, this reaction mixture liquid was poured in methanol in about 10 times the amount of the reaction mixture liquid of methanol, and a polymer thus formed was isolated. This polymer was dried at 40°C for
25 6 hours to obtain 9.8 g of a polymer (H). The weight-average

molecular weight of this polymer was 200000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (F), 3.5 g of the polymer (G), 0.5 g of the polymer (H), 0.01 g of diphenylsilicone (produced by Shin-Etsu Chemical Co., Ltd.) having a viscosity of 500 CS and 0.05 g of n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate, and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 3.

Table 3

item	unit	Example 5			Example 6			Example 7		
		Polymer F	Polymer G	Polymer H	Polymer F	Polymer G	Polymer H	Polymer F	Polymer G	Polymer H
Molecular weight (Mw)	g/mol	7500	200000	210000	7500	200000	210000	10000	200000	200000
Mixing ratio	% by weight	55	35	10	55	35	10	60	35	5
Antioxidant E	% by weight	0			0.5			0.5		
Silicone amount D	% by weight	0			0.1			0.1		
Fluidity (MI)	g/10 minutes	18			18			22		
Water absorption	%	0.09			0.09			0.08		
Heat resistance (Tg)	°C	147			147			152		
Relative permittivity	-	2.3			2.3			2.2		
Bending strength	MPa	80			80			80		
Transparency	%	85			85			85		
Birefringence	-	1×10^{-6}			1×10^{-6}			1×10^{-6}		
Change in hue	-	0.35			0.12			0.11		

COMPARATIVE EXAMPLE 3

Placed in a 100-mL flask were 10.0 g of indene and 30.0 g of nitrobenzene, and 0.05 g of FeCl_3 was added thereto at 0°C, thereby being allowed to react for 12 hours. Thereafter, 0.05 g of methanol was added to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (F). The weight-average molecular weight of this polymer was 7500.

Placed in a 100-mL flask were 20.0 g of styrene and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, 60 g of distilled water and 0.01 g of calcium phosphate were added to the monomer mixture, and the mixture was allowed to react at 70°C for 12 hours with being stirred. A granular polymer thus obtained was isolated and washed with hydrochloric acid. Subsequently, the polymer was dried at 50°C for about 2 hours to obtain a polymer (G). The weight-average molecular weight of the polymer obtained was 200000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (F) and 4.0 g of the polymer (G), and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a white precipitate

of a resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 4.

Table 4

item	unit	Comparative Example 3	
		Polymer F	Polymer G
Molecular weight (Mw)	g/mol	7500	200000
Mixing ratio	% by weight	60	40
Antioxidant E	% by weight	0	
Silicone amount D	% by weight	0	
Fluidity (MI)	g/10 minutes	17	
Water absorption	%	0.10	
Heat resistance (Tg)	°C	142	
Relative permittivity	-	2.3	
Bending strength	MPa	75	
Transparency	%	55	
Birefringence	-	Could not be measured	
Change in hue	-	0.35	

EXAMPLE 8

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Placed in a 100-mL flask were 9.95 g of indene, 0.05 g of vinylpyridine and 30.0 g of methylene chloride, and 0.01 g of FeCl_3 was added thereto at -40°C , thereby being allowed to react for 24 hours. Thereafter, 0.05 g of methanol was added at room temperature to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added

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to 100 g of methanol to obtain 9.8 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (I). The weight-average molecular weight of this polymer was 97000.

5 Placed in a 100-mL flask were 19.9 g of styrene, 0.1 g of methacrylic acid and 0.1 g of benzoyl peroxide, and the mixture was stirred to dissolve. Then, the mixture was sealed and allowed to react at 70°C for 12 hours with reflux. The polymer thus obtained was granulated and then washed with
10 methanol. Subsequently, the polymer was dried at 50°C for about 8 hours to obtain a polymer (J). The weight-average molecular weight of the polymer obtained was 250000.

 Dissolved in 20 g of toluene were 6.0 g of the polymer (I), 4.0 g of the polymer (J), 0.01 g of diphenylsilicone having
15 a viscosity of 500 CS and 0.05 g of n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate, and the mixture was added to about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired resin composition. This resin composition was hot-pressed to
20 produce a molding material having a thickness of 2 mm. This molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 5.

EXAMPLE 9

Placed in a 100-mL flask were 9.95 g of indene, 0.05 g of vinylpyridine and 30.0 g of toluene, and 0.01 g of AlCl_3 ,
5 was added thereto at -4°C , thereby being allowed to react for 24 hours. Thereafter, 0.05 g of methanol was added at room temperature to this reaction mixture liquid, and then the liquid was stirred to obtain a homogeneous solution. The homogeneous solution thus obtained was gradually added to 100 g of methanol
10 to obtain 9.7 g of a white precipitate. This white precipitate was dried under reduced pressure to obtain a polymer (I). The weight-average molecular weight of this polymer was 50000.

Placed in a 100-mL flask were 19.8 g of styrene, 0.2 g of methacrylic acid and 0.1g of benzoyl peroxide, and the
15 mixture was stirred to dissolve. Then, the mixture was sealed and allowed to react at 70°C for 12 hours with reflux. A polymer thus obtained was granulated and then washed with methanol. Subsequently, the polymer was dried at 50°C for about 8 hours to obtain a polymer (J). The weight-average molecular weight
20 of the polymer obtained was 250000.

Dissolved in 20 g of toluene were 6.0 g of the polymer (I), 4.0 g of the polymer (J), 0.01 g of diphenylsilicone (produced by Shin-Etsu Chemical Co., Ltd.) having a viscosity of 500 CS and 0.05 g of n-octadecyl-3-(4-hydroxy-
25 3,5-t-dibutylphenyl)propionate, and the mixture was added to

about 300 g of methanol to precipitate a solid. This solid was dried at 40°C for 6 hours to obtain a desired resin composition. This resin composition was hot-pressed to produce a molding material having a thickness of 2 mm. This
5 molding material was used as a sample fragment. The above-mentioned evaluations were carried out using this sample fragment. The evaluation results are shown in Table 5.

Table 5

item	unit	Example 8		Example 9	
		Polymer I	Polymer J	Polymer I	Polymer J
Molecular weight {Mw}	g/mol	97000	250000	50000	250000
Mixing ratio	% by weight	60	40	60	40
Heterocycle amount	mol%	0.55	0	0.55	0
Carboxyl group amount	mol%	0	0.53	0	1.06
Heterocycle/carb oxyl group ratio	mol/mol	1.04		0.52	
Antioxidant E	% by weight	0.5		0.5	
Silicone amount D	% by weight	0.1		0.1	
Fluidity (MI)	g/10 minutes	15		12	
Water absorption	%	0.10		0.11	
Heat resistance (Tg)	°C	147		142	
Relative permittivity	-	2.3		2.3	
Bending strength	Mpa	80		82	
Transparency	%	85		86	
Birefringence	-	1×10^{-6}		1×10^{-6}	
Change in hue	-	0.12		0.11	

COMPARATIVE EXAMPLE 4

An experiment was carried out in the same manner as in Example 7 except using only 10.0 g of indene and not using vinylpyridine and methylene chloride in the synthesis of the polymer (I), and using only 20.0 g of styrene and not using methacrylic acid in the synthesis of the polymer (H). The above-mentioned evaluations were conducted using this sample fragment. The evaluation results are shown in Table 6.

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COMPARATIVE EXAMPLE 5

An experiment was carried out in the same manner as in Example 7 except not using 0.01 g of diphenylsilicone having a viscosity of 500 CS (produced by Shin-Etsu Chemical Co., Ltd.) and 0.05 g of n-octadecyl-3-(4-hydroxy-3,5-t-dibutylphenyl)propionate. The above-mentioned evaluations were conducted using this sample fragment. The evaluation results are shown in Table 6.

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Table 6

item	unit	Comparative Example 4		Comparative Example 5	
		Polymer I	Polymer J	Polymer I	Polymer J
Molecular weight (Mw)	g/mol	15000	250000	15000	250000
Mixing ratio	% by weight	60	40	60	40
Heterocycle amount	mol%	0	0	0.55	0
Carboxyl group amount	mol%	0	0	0	0.53
Heterocycle/carboxyl group ratio	mol/mol	-		1.04	
Antioxidant E	% by weight	0.5		0	
Silicone amount D	% by weight	0.1		0	
Fluidity (MI)	%/10 minutes	14		15	
Water absorption	%	0.09		0.09	
Heat resistance (Tg)	°C	142		143	
Relative permittivity	-	2.2		2.2	
Bending strength	MPa	80		80	
Transparency	%	42		85	
Birefringence	-	1×10^{-6}		1×10^{-6}	
Change in hue	-	0.15		3.7	

INDUSTRIAL APPLICABILITY

The present invention can provide resin compositions having low hygroscopicity, low birefringence and low permittivity, being excellent in fluidity, causing little change in color upon heating, and excelling in mold release characteristics in injection molding. Furthermore, the use of a molding material, a sheet or a film obtained by molding these resin compositions can provide an optical part having low hygroscopicity, low birefringence and low permittivity.

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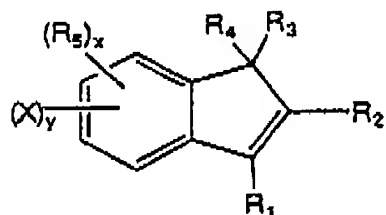
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The amended claims under PCT Article 34

CLAIMS

1. (Amended) A resin composition (a) for use in optical parts, comprising the following polymers (A), and (B) and/or (C):
- (A) a polymer comprising one or more kinds of indene and indene derivatives represented by the following general formula (I);
- (B) a polymer comprising polystyrene or a polystyrene derivative; and
- (C) a polymer comprising a monomer copolymerizable with styrene or a styrene derivative:

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(I)

- (wherein R_1 , R_2 , R_3 , R_4 , and R_5 may be the same or different, and each represents a hydrogen atom; a monovalent hydrocarbon group containing a nitrogen atom, an oxygen atom or a silicon atom; an alkyl group having 1 to 6 carbon atoms; or a monovalent aromatic hydrocarbon group. X represents a hydrogen atom, a halogen atom, an acyl group, an alkoxy group or a nitrile group. x represents 0 or an integer of 1 to 4, and y represents an integer of 1 to 4, where $x + y = 4$.)

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2. (Amended) The resin composition (a) according to claim 1,
wherein a diphenylsilicone (D) and/or a phenolic antioxidant
(E) are/is added to the resin composition comprising the
5 polymers (A), and (B) and/or (C).

3. The resin composition (a) according to claim 1 or 2, wherein
the saturated water absorption is 0.4% or less, and the
birefringence in stretching the resin composition by 200% is
10 in the range of -2×10^{-6} to 2×10^{-6} .

4. The resin composition (a) according to any one of claims
1 to 3, wherein the weight-average molecular weight of the
polymer (A) is lower than 80000.

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5. The resin composition (a) according to any one of claims
1 to 4, wherein the weight-average molecular weight(s) of the
polymer (B) and/or the polymer (C) are/is 50000 or higher.

20 6. The resin composition (a) according to any one of claims
1 to 5, wherein the content of the polymer (A) is 30 to 90%
by weight of the total of the resin composition (a).

7. A resin composition (b) comprising the following polymers
25 (F), (G) and (H):

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(F) a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I);

(G) a polymer comprising polystyrene or a polystyrene derivative; and

- 5 (H) a graft polymer having a structure wherein a polymer comprising at least one kind of indene and an indene derivative represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative.

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8. The resin composition (b) according to claim 7, wherein a diphenylsilicone (D) and/or a phenolic antioxidant (E) are/is added to the resin composition comprising the polymers (F), (G) and (H).

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9. The resin composition (b) according to claim 7 or 8, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

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10. The resin composition (b) according to any one of claims 7 to 9, wherein the weight-average molecular weight of the polymer (F) is 4000 or higher.

- 25 11. The resin composition (b) according to any one of claims

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7 to 10, wherein the weight-average molecular weights of the polymer (G) and the polymer (H) are 50000 or higher.

12. The resin composition (b) according to any one of claims 5 7 to 11, wherein the content of the polymer (F) is 30 to 90% by weight of the total of the resin composition (b).

13. A resin composition (c) comprising the following polymers (I) and (J), diphenylsilicone (D), and a phenolic antioxidant (E):

(I) a polymer comprising one or more kinds of indene and indene derivatives represented by the general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof; and

15 (J) a polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a carboxyl group and/or a phenolic hydroxyl group in a side chain thereof.

20 14. The resin composition (c) according to claim 13, wherein the saturated water absorption is 0.4% or less, and the birefringence in stretching the resin composition by 200% is in the range of -2×10^{-6} to 2×10^{-6} .

25 15. The resin composition (c) according to claim 13 or 14,

wherein the content of the heterocyclic structure in the polymer (I) is 0.01 to 5 mol% of the total of the resin composition (c), and the content of the carboxyl group and/or the phenolic hydroxyl group in the polymer (J) are/is 0.01 to 5 mol% of the total of the resin composition (c).

16. The resin composition (c) according to any one of claims 13 to 15, wherein the molar ratio of the heterocyclic structure to the carboxyl group and/or the phenolic hydroxyl group is 0.1 to 10.0.

17. The resin composition (c) according to any one of claims 13 to 16, wherein the content of the polymer (I) is 30 to 90% by weight of the total of the resin composition (c).

15

18. The resin composition (c) according to any one of claims 13 to 17, wherein the addition amount of the diphenylsilicone (D) is 0.01 to 1.0% by weight of the total of the resin composition (c), and the addition amount of the phenolic antioxidant (E) is 0.1 to 3.0% by weight of the total of the resin composition (c).

19. (Amended) A molding material for use in optical parts, the molding material being obtained by molding a resin composition selected from the resin composition (a) according to claim

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1, the resin composition (b) according to claim 7 and the resin composition (c) according to claim 13.

20. (Amended) A sheet for use in optical parts, the sheet being
5 obtained from a resin composition selected from the resin composition (a) according to claim 1, the resin composition (b) according to claim 7 and the resin composition (c) according to claim 13.

10 21. (Amended) A film for use in optical parts, the film being obtained from a resin composition selected from the resin composition (a) according to claim 1, the resin composition (b) according to claim 7 and the resin composition (c) according to claim 13.

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22. An optical part using the molding material, the sheet or the film according to any one of claims 19 to 21.

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ABSTRACT OF THE DISCLOSURE

Low-hygroscopicity low-birefringence resin compositions. One of the compositions is a resin composition

5 (a) comprising the following polymers (A), and (B) and/or (C). Another is a resin composition (b) comprising the following polymers (A), (B) and (H). Still another is a polymer comprising the following polymers (I) and (J), diphenylsilicone (D), and a phenolic antioxidant (E).

10 (A) A polymer comprising one or more kinds of indene and indene derivatives represented by the following general formula (I). (B) A polymer comprising polystyrene or a polystyrene derivative. (C) A polymer comprising a monomer copolymerizable with styrene or a styrene derivative. (H)

15 A graft polymer having a structure wherein a polymer comprising at least one kind of indene and an indene derivative represented by the general formula (I) bonds to a side chain of a polymer comprising a monomer copolymerizable with styrene or a styrene derivative. (I) A polymer comprising one or more kinds of

20 indene and indene derivatives represented by the general formula (I), wherein the polymer has a heterocyclic structure in a side chain thereof. (J) A polymer comprising styrene or a styrene derivative, and a monomer copolymerizable with styrene or a styrene derivative, wherein the polymer has a

25 carboxyl group and/or a phenolic hydroxyl group in a side chain

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thereof.



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Attorney's Docket No. TOYAMA 83.001APC**DECLARATION AND POWER OF ATTORNEY - USA PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is

sought on the invention entitled LOW-HYGROSCOPICITY LOW- BIREFRINGENCE RESIN
COMPOSITIONS MOLDING MATERIAL, SHEET OR FILM OBTAINED THEREFROM, AND
the specification of which: OPTICAL PART

- (a) ☐ is attached hereto; or
- (b) ☒ was filed on 12-27-01 as Application
No. 10/019,753 or Express Mail No., as Application No.
not
yet known _____ and was amended
on _____ (if applicable); or
- (c) ☐ was described and claimed in PCT International Application No.
PCT/JP 00/04215 filed on June 27, 2000
and as amended under PCT Article 19 on _____
(if any) and/or under PCT Article 34 on _____ (if any).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) listed below and have also identified below any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed for the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

COUNTRY (OR INDICATE IF PCT)	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED UNDER 37 U.S.C. § 119
Japan	11-181181	28/06/1999	<input checked="" type="radio"/> YES <input type="radio"/> NO
Japan	11-181182	28/06/1999	<input checked="" type="radio"/> YES <input type="radio"/> NO
Japan	2000-24774	28/01/2000	<input checked="" type="radio"/> YES <input type="radio"/> NO
Japan	2000-24775	28/01/2000	<input checked="" type="radio"/> YES <input type="radio"/> NO

Japan	2000-24776	28/01/2000	<input checked="" type="radio"/> YES	<input type="radio"/> NO
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I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below, and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S.A. Application(s)

Application No.: _____ Filing Date: _____ Status: _____

POWER OF ATTORNEY: I hereby appoint the registrants of Knobbe, Martens, Olson & Bear, LLP, 620 Newport Center Drive, Sixteenth Floor, Newport Beach, California 92660, Telephone (949) 760-0404, Customer No. 20,995.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

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